Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

In the Claims:

Please amend the claims as follows:

1. (currently amended) A connection between a pair of electrical components comprising:
a male component having an array of spaced apart bumps;
a female component having a matching array of spaced apart wells;
bonding material substantially filling said wells; and
wherein each of said bumps extends into the material in its matching well and bonds with said bonding material to form a connection to said female component.

2. (original) The connection of claim 1 wherein said bumps are gold stud bumps.

3. (original) The connection of claim 1 wherein said bonding material is solder.

4. (original) The connection of claim 1 wherein said components are alignment sensitive.

5. (cancelled).

6. (original) The connection of claim 3 wherein said male component or said female component is an electrical component.

7. (original) The connection of claim 3 wherein said solder is indium-based.

8. (currently amended) The connection of claim 6 wherein [one of] said electrical component is an integrated circuit chip.

9. (currently amended) The connection of claim 6 wherein [one of] said electrical component is a module access cable.

10. (currently amended) The connection of claim 6 wherein [one of] said electrical component is an interconnection circuit.

11. (currently amended) A method for connecting a pair of electrical components comprising the steps of:

providing an array of bumps on a male component;

providing a matching array of wells in a female component;

filling said wells with bonding material;

aligning said male and female components and inserting said bumps into the material in said wells; and,

activating said bonding material to attach said female component to said male component.

12. (cancelled).

13. (original) A method for aligning a pair of components comprising the steps of:

providing an array of bumps on a male component;

providing a matching array of wells in a female component;

filling said wells with bonding material;

positioning said female and male components relative to one another and inserting said bumps in said wells;

monitoring an alignment-sensitive performance parameter for the combined components;

optimizing said positioning by maximizing said performance parameter; and,

bonding said bumps to said wells using said bonding material.

14. (new) A connection between a pair of components comprising:

a male component having an array of bumps spaced apart less than 200 microns;

a female component having a matching array of wells spaced apart less than 200 microns;

bonding material in said wells; and

wherein each of said bumps extends into its matching well and bonds to said bonding material to form a connection to said female component.

15. (new) A method for connecting a pair of electrical components comprising the steps of:
providing an array of bumps on a male component;
providing a matching array of wells in a female component;
using a squeegee, filling said wells with bonding material;
aligning said male and female components and inserting said bumps in said wells; and
activating said bonding material to attach said female component to said male component.

16. (new) The method of claim 11 in which the said bump material is gold and said bonding material is solder.